



Parameter	Rating	Units
Drain-to-Source Voltage - V_{DS}	415	V
Max On-Resistance - $R_{DS(on)}$	14	Ω
Max Power	2.5	W

Features

- 415V Drain-to-Source Voltage
- Depletion Mode Device Offers Low $R_{DS(on)}$ at Cold Temperatures
- Low On-Resistance: 8Ω (Typical) @ 25°C
- Low $V_{GS(off)}$ Voltage: -2.0V to -3.6V
- High Input Impedance
- Low Input and Output Leakage
- Small Package Size SOT-223
- PC Card (PCMCIA) Compatible
- PCB Space and Cost Savings

Applications

- Support Component for LITELINK™ Data Access Arrangement (DAA)
- Telecom
- Normally-On Switches
- Ignition Modules
- Converters
- Security
- Power Supplies

Description

The CPC5603 is an N-channel, depletion mode Field Effect Transistor (FET) that utilizes IXYS Integrated Circuits Division's proprietary third-generation vertical DMOS process. The third generation process realizes world class, high voltage MOSFET performance in an economical silicon gate process. The vertical DMOS process yields a highly reliable device particularly in difficult application environments such as telecommunications, security, and power supplies.

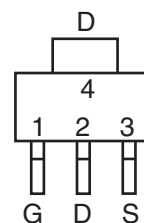
One of the primary applications for the CPC5603 is as a linear regulator/hook switch for the LITELINK™ family of Data Access Arrangements (DAA) Devices CPC5620A, CPC5621A, and CPC5622A.

The CPC5603 has a typical on-resistance of 8Ω , a drain-to-source voltage of 415V and is available in the SOT-223 package. As with all MOS devices, the FET structure prevents thermal runaway and thermal-induced secondary breakdown.

Ordering Information

Part #	Description
CPC5603CTR	N-Channel Depletion Mode FET, SOT-223 Pkg. Tape and Reel (1000/Reel)

Package Pinout



Pin Number	Name
1	GATE
2	DRAIN
3	SOURCE
4	DRAIN



Absolute Maximum Ratings @ 25°C

Parameter	Symbol	Ratings	Units
Drain-to-Source Voltage	V_{DS}	415	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Total Package Dissipation	P	2.5	W
Operational Temperature	T_A	-40 to +85	°C
Storage Temperature	T_A	-40 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

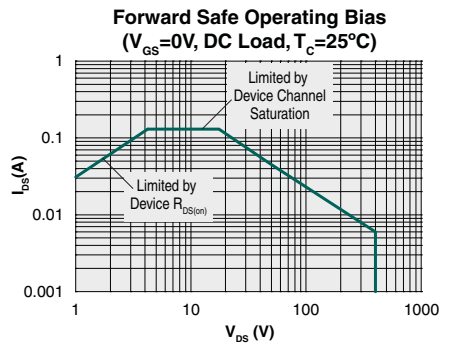
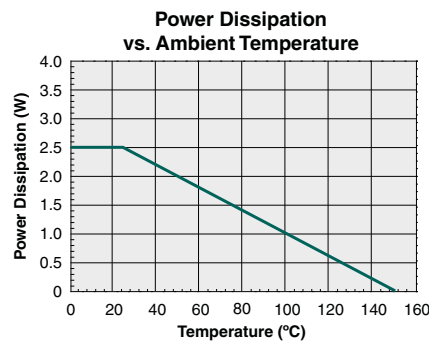
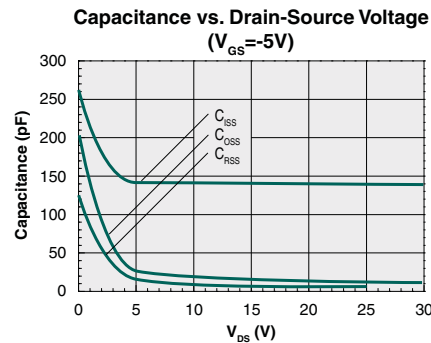
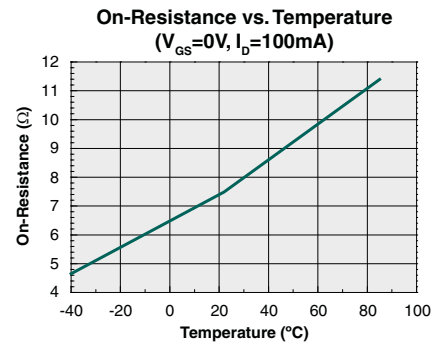
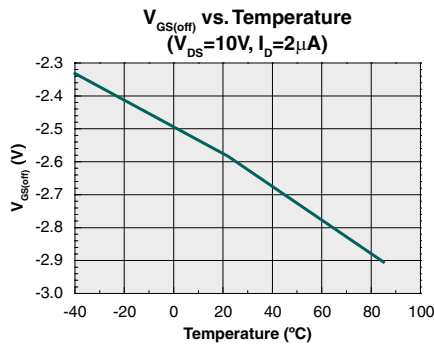
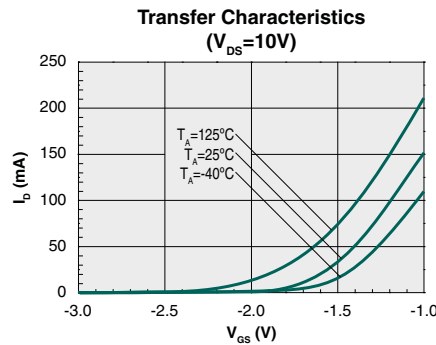
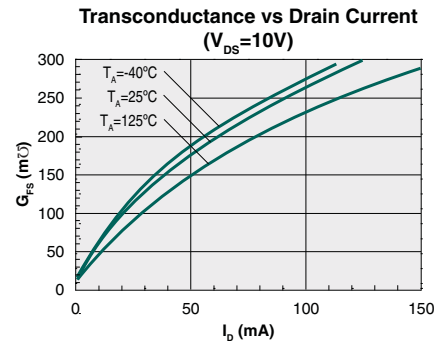
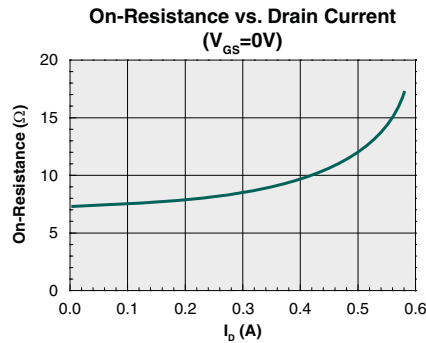
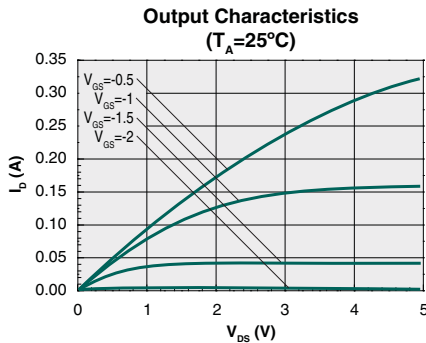
Electrical Characteristics @25°C (Unless Otherwise Specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Gate-to-Source Off Voltage	$V_{GS(off)}$	$I_D = 2\mu A, V_{DS} = 10V, V_{DS} = 100V$	-2		-3.6	V
Drain-to-Source Leakage Current	$I_{DS(off)}$	$V_{GS} = -5V, V_{DS} = 250V$	-	-	20	nA
		$V_{GS} = -5V, V_{DS} = 415V$	-	-	1	μA
Drain Current	I_D	$V_{GS} = -2.7V, V_{DS} = 5V, V_{DS} = 50V$	-	-	5	mA
		$V_{GS} = -0.57V, V_{DS} = 5V$	130	-	-	mA
On Resistance	$R_{DS(on)}$	$V_{GS} = -0.35V, I_{DS} = 50mA$	-	8	14	Ω
Gate Leakage Current	I_{GSS}	$V_{GS} = 10V, V_{GS} = -10V$	-	-	0.1	μA
Gate Capacitance	C_{ISS}	$V_{DS} = V_{GS} = 0V$	-	-	300	pF

Thermal Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Thermal Resistance	$R_{\theta JC}$	-	-	-	14	°C/W

Performance Data*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC5603C	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
CPC5603C	260°C for 30 seconds

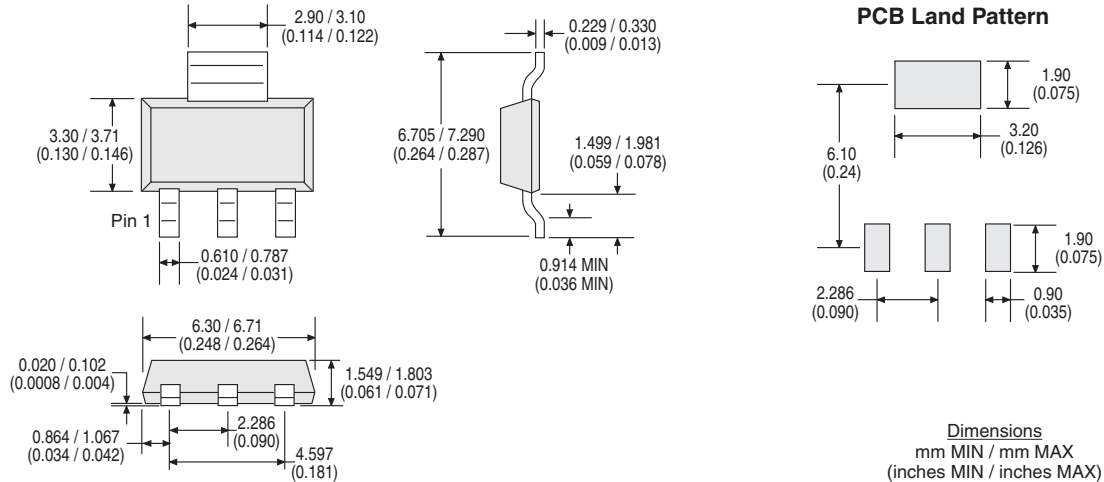
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable, and the use of a short drying bake may be necessary. Chlorine-based or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

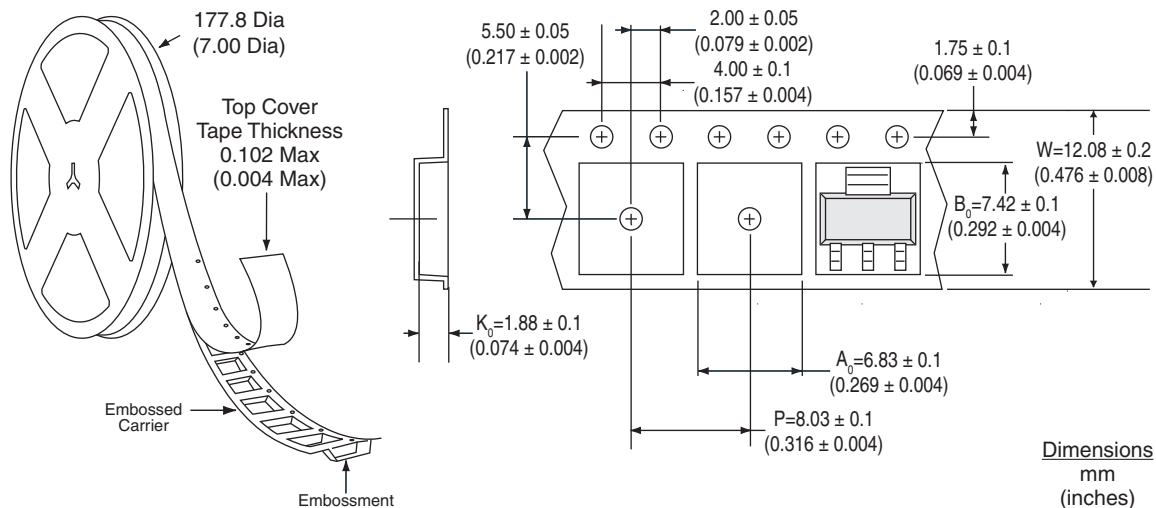


MECHANICAL DIMENSIONS

CPC5603C



CPC5603CTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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